



11-8-05

IFU

Docket No. 8201/Y01/SYNX/JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Re: Inventor(s): Michael R. Rice, Eric A. Enghardt, Vinay Shah, Martin R. Elliott, Robert B. Lowrance and Jeffrey C. Hudgens
Title: SYSTEMS AND METHODS FOR TRANSFERRING SMALL LOT SIZE SUBSTRATE CARRIERS BETWEEN PROCESSING TOOLS
Serial No.: 10/764,620
Filed: January 26, 2004
Examiner: Kasenge, Charles R
Group Art Unit: 2125

Transmitted herewith is:

- ☒ PTO Form 1449;
☒ Information Disclosure Statement with eleven cited references (copy of eight references enclosed); and
☒ Return Postcard.

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	N/A	- 20 =	-0-	X \$50.00	\$0.00
Independent Claims	N/A	- 3 =	-0-	X \$200.00	\$0.00
Basic Filing Fee				\$790.00	\$0.00
TOTAL FEES					PAID

☐ The Commissioner is hereby authorized to charge \$0.00 to Deposit Account No. 04-1696.

☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 04-1696. A duplicate copy of this transmittal is enclosed.

☒ Please address all future correspondence to: Customer # 41161
Dugan & Dugan, PC
55 South Broadway
Tarrytown, NY 10591

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Express Mail Receipt No. EV605115681US

Date of Deposit: November 7, 2005

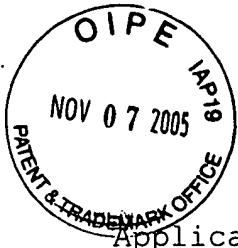
Signature:

Respectfully submitted,

Brian M. Dugan
Registration No. 41,720
(914) 332-9081

Express Mail Label No. EV605115681US

PATENTS
8201/Y01/SYNX/JW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Michael R. Rice, Eric A. Englhardt, Vinay Shah, Martin R. Elliott, Robert B. Lowrance and Jeffrey C. Hudgens

Serial No. : 10/764,620

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For : SYSTEMS AND METHODS FOR TRANSFERRING SMALL LOT SIZE SUBSTRATE CARRIERS BETWEEN PROCESSING TOOLS

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Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97,
applicants wish to call the attention of the Examiner to the
following references:

U.S. Patent No. 5,256,204, Hong J. Wu

U.S. Patent No. 5,668,056, Wu et al.

U.S. Patent No. 5,976,199, Wu et al.

Foreign Art Reference No. JP 2000012646 A (Japan)

"300mm single-wafer transport", July 1999, Solid State Technology - semiconductor manufacturing and wafer fabrication, Semicon West '99 Product Spotlight, pg. 5.

"300mm single-wafer handling", April 2000, Solid State Technology, Product News, <www.solid-state.com>, pg. 99.

Griessing, Juergen et al., "Assessing the feasibility of a 300-mm test and monitor wafer handling and logistics system", July 2000, Micro: The 300-mm Imperative, pgs. 1-19.

"The Leading Company in Micro environment", January 3, 2002, Incam Solutions Company, pgs.1-2.

"Improved wafer isolation and additional flexibility", January 3, 2002, Incam Solutions Company SWIF technology, pgs. 1-2.

"SEMI standards compliance" and "Related SEMI standards", January 3, 2002, Incam Solutions Related standards, pg. 1.

"Single Wafer Lots Solution", January 3, 2002, Incam Solutions References, pg. 1.

These references are also listed on the accompanying
Information Disclosure Statement (Form PTO-1449).

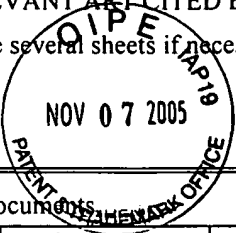
Consideration of the foregoing in relation to this patent
application is respectfully requested.

Respectfully Submitted,

A handwritten signature in dark ink, appearing to read 'Brian M. Dugan', with a long horizontal line extending to the right.

Brian M. Dugan, Esq.
Registration No. 41,720
Dugan & Dugan, PC
Attorneys for Applicants
(914) 332-9081

Dated: November 7, 2005
Tarrytown, New York

U.S. Department of Commerce, Patent and Trademark Office LIST OF RELEVANT ART CITED BY APPLICANT (Use several sheets if necessary)				Docket No.: 8201/Y01/SYNX/JW		Serial No.: 10/764,620	
				Applicants: Michael R. Rice, et al			
				Filing Date: January 26, 2004		Group: 2125	
U.S. Patent Documents							
*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
	US-1	5,256,204	10/26/93	Hong J. Wu			
	US-2	5,668,056	09/16/97	Wu et al.			
	US-3	5,976,199	11/02/99	Wu et al.			
	US-4						
	US-5						
	US-6						
	US-7						
	US-8						
	US-9						
	US-10						
	US-11						
Foreign Patent Documents							Translation
		Document Number	Date	Country	Class	Subclass	Yes No
	F-1	JP 2000012646 A2	01/14/00	Japan			Abstract Only
	F-2						
	F-3						
	F-4						
	F-5						
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	OT-1	"300mm single-wafer transport", July 1999, Solid State Technology - semiconductor manufacturing and wafer fabrication, Semicon West '99 Product Spotlight, pg. 5.					
	OT-2	"300mm single-wafer handling", April 2000, Solid State Technology, Product News, <www.solid-state.com>, pg. 99.					
	OT-3	Griessing, Juergen et al., "Assessing the feasibility of a 300-mm test and monitor wafer handling and logistics system", July 2000, Micro: The 300-mm Imperative, pgs. 1-19.					
Examiner			Date Considered				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.							

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U.S. Patent Documents							
*Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate	
	US-12						
	US-13						
	US-14						
	US-15						
	US-16						
	US-17						
	US-18						
	US-19						
	US-20						
	US-21						
	US-22						

Foreign Patent Documents							Translation	
	Document Number	Date	Country	Class	Subclass	Yes	No	
	F-6							
	F-7							
	F-8							
	F-9							
	F-10							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	
OT-4	"The Leading Company in Micro environment", January 3, 2002, Incam Solutions Company, pgs. 1-2.
OT-5	"Improved wafer isolation and additional flexibility", January 3, 2002, Incam Solutions Company SWIF technology, pgs. 1-2.
OT-6	"SEMI standards compliance" and "Related SEMI standards", January 3, 2002, Incam Solutions Related standards, pg. 1.

Examiner	Date Considered
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U.S. Patent Documents							
*Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate	
	US-23						
	US-24						
	US-25						
	US-26						
	US-27						
	US-28						
	US-29						
	US-30						
	US-31						
	US-32						
	US-33						

Foreign Patent Documents							Translation	
	Document Number	Date	Country	Class	Subclass	Yes	No	
	F-11							
	F-12							
	F-13							
	F-14							
	F-15							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	
OT-7	"Single Wafer Lots Solution", January 3, 2002, Incam Solutions References, pg. 1.
OT-8	
OT-9	

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